



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTS3050EJ	Issued	11. August 2021
MA#	MA005353588		
Package	PG-TDSO-8-31	Weight*	67.45 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.461	2.17	2.17	21666	21666
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		563	
	non noble metal	iron	7439-89-6	0.760	1.13		11265	
	non noble metal	copper	7440-50-8	30.851	45.73	46.93	457388	469357
wire	non noble metal	copper	7440-50-8	0.321	0.48	0.48	4758	4758
encapsulation	organic material	carbon black	1333-86-4	0.096	0.14		1428	
	plastics	epoxy resin	-	3.757	5.57		55701	
	inorganic material	silicondioxide	60676-86-0	28.258	41.90	47.61	418951	476080
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7372	7372
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12228	12228
glue	plastics	epoxy resin	-	0.101	0.15		1494	
	noble metal	silver	7440-22-4	0.475	0.70	0.85	7045	8539
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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